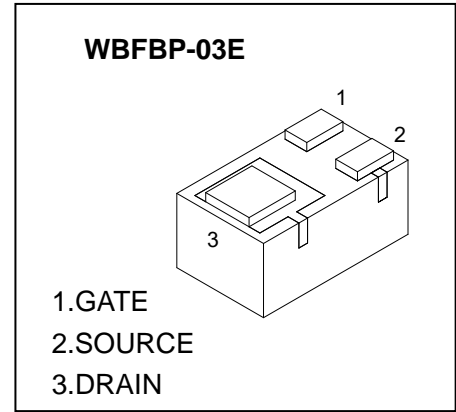




WBFBP-03E Plastic-Encapsulate MOSFETS

CJAA3139K P-Channel MOSFET

$V_{GS} = 0V$ $V_{DS} = -10V$ $I_D = -0.66A$	$R_{\theta JA} = 1250^{\circ}C/W$ $T_J = 25^{\circ}C$	$V_{GS} = 0V$ $V_{DS} = -10V$ $I_D = -0.66A$
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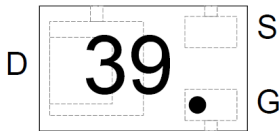
FEATURE

- Lead Free Product is Acquired
- Surface Mount Package
- P-Channel Switch with Low $R_{DS(on)}$
- Operated at Low Logic Level Gate Drive
- ESD Protected Gate
- Complementary to CJAA3134K

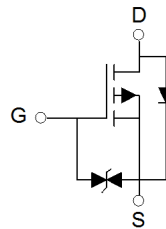
APPLICATION

- Load/ Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

MARKING:



9ei Jj UYbh 7 jfW Jh



ABSOLUTE MAXIMUM RATINGS ($T_a=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current (note 1)	I_D	-0.66	A
Pulsed Drain Current ($t_p=10\mu s$)	I_{DM}	-1.2	A
Power Dissipation (note 2)	P_D	100	mW
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	1250	$^{\circ}C/W$
Operation Junction and Storage Temperature Range	T_J, T_{STG}	-55~ 150	$^{\circ}C$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T_L	260	$^{\circ}C$

MOSFET ELECTRICAL CHARACTERISTICS

$T_a=25\text{ }^\circ\text{C}$ unless otherwise specified

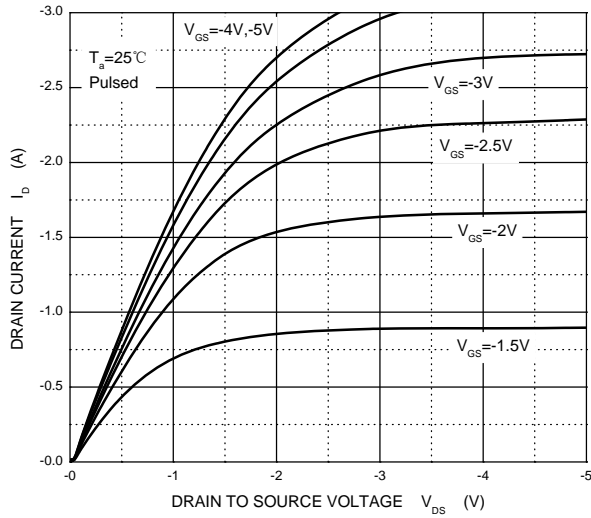
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-20			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 10V, V_{DS} = 0V$			± 20	μA
Gate threshold voltage (note 2)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.35		-1.1	V
Drain-source on-resistance(note 2)	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -1A$		430	520	$m\Omega$
		$V_{GS} = -2.5V, I_D = -0.8A$		624	700	$m\Omega$
		$V_{GS} = -1.8V, I_D = -0.5A$		950		$m\Omega$
Forward transconductance(note 2)	g_{FS}	$V_{DS} = -10V, I_D = -0.54A$		1.2		S
Diode forward voltage	V_{SD}	$I_S = -0.5A, V_{GS} = 0V$			-1.2	V
DYNAMIC PARAMETERS(note 4)						
Input Capacitance	C_{iss}	$V_{DS} = -16V, V_{GS} = 0V, f = 1MHz$		113	170	pF
Output Capacitance	C_{oss}			15	25	pF
Reverse Transfer Capacitance	C_{rss}			9	15	pF
SWITCHING PARAMETERS (note 4)						
Turn-on delay time (note 3)	$t_{d(on)}$	$V_{DD} = -4.5V, V_{GS} = -10V,$ $I_D = -200mA, R_{GEN} = 10\Omega$		9		ns
Turn-on rise time (note 3)	t_r			5.8		ns
Turn-off delay time (note 3)	$t_{d(off)}$			32.7		ns
Turn-off fall time (note 3)	t_f			20.3		ns

Notes :

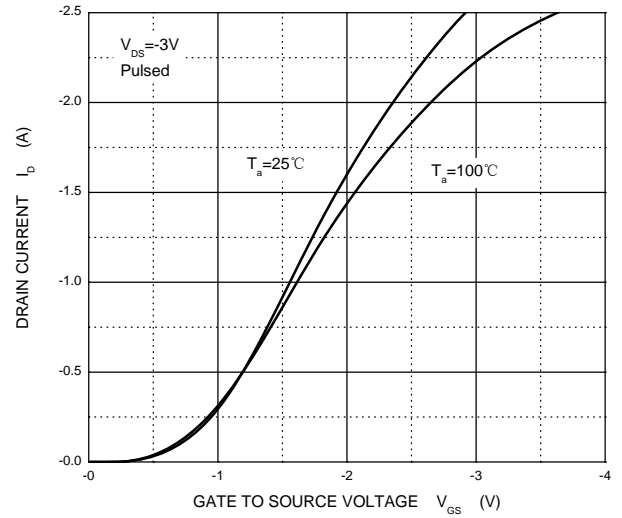
1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse width=300 μs , duty cycle $\leq 2\%$.
3. Switching characteristics are independent of operating junction temperatures.
4. Guaranteed by design, not subject to producing.

Typical Characteristics

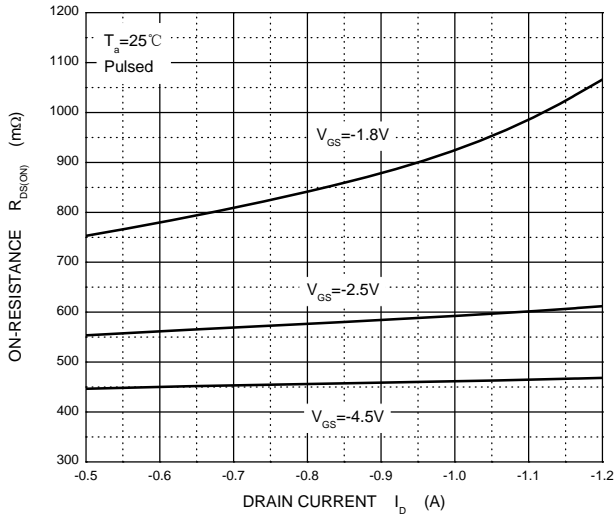
Output Characteristics



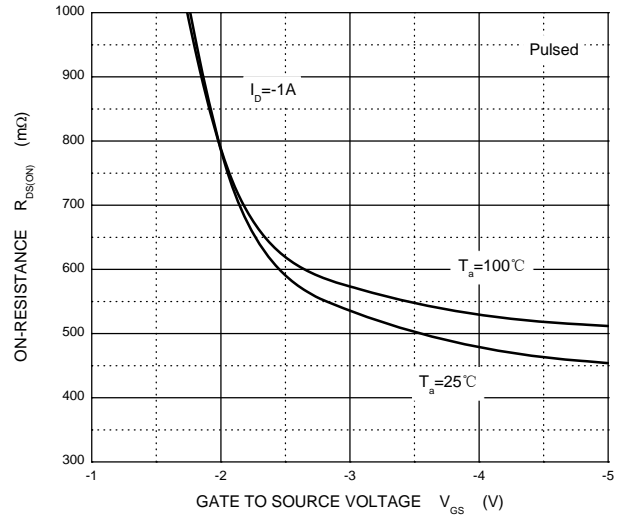
Transfer Characteristics



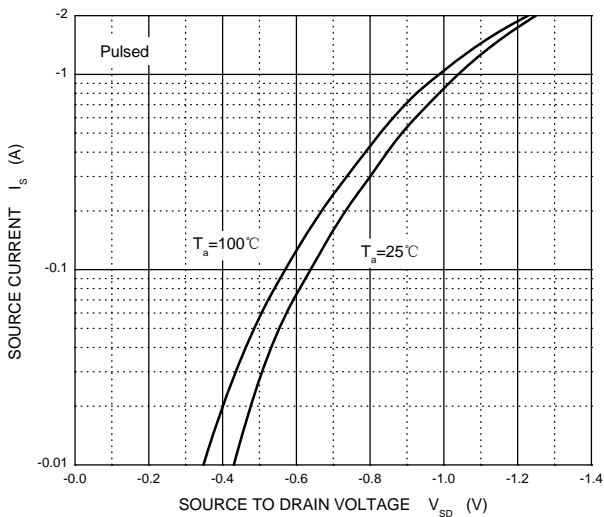
$R_{DS(ON)}$ — I_D



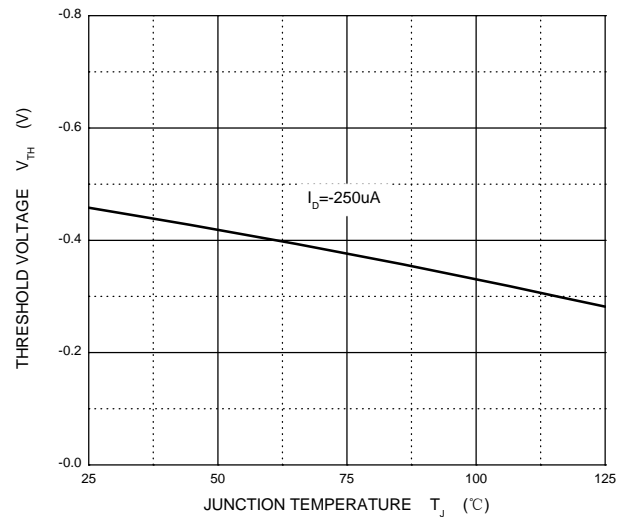
$R_{DS(ON)}$ — V_{GS}



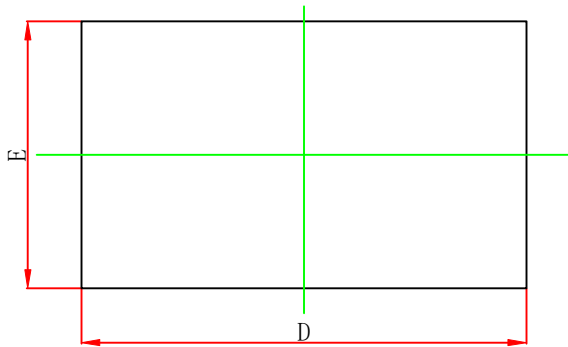
I_S — V_{SD}



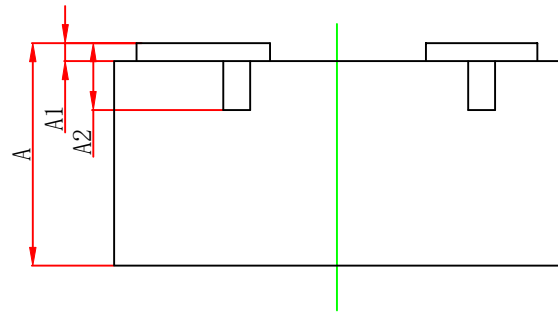
Threshold Voltage



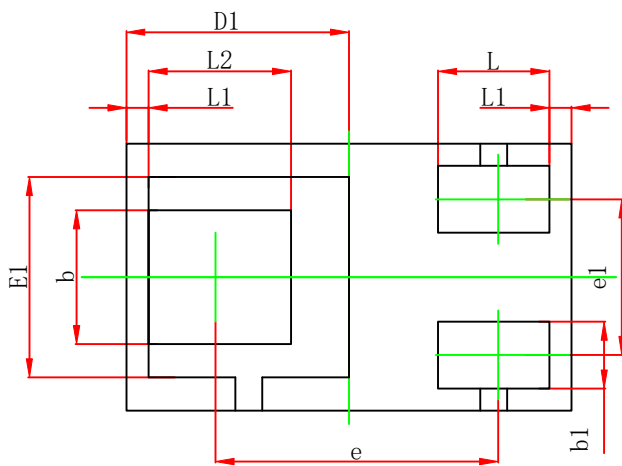
WBFBP-03E Package Outline Dimensions



TOP VIEW



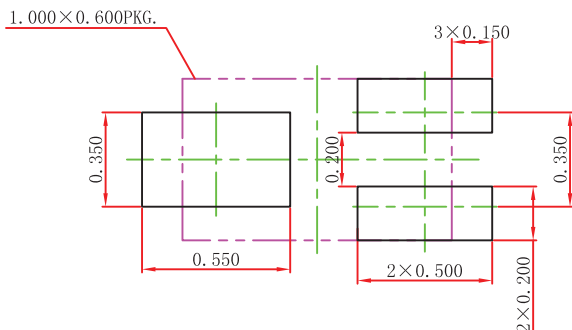
SIDE VIEW



BOTTOM VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.450	0.550	0.018	0.022
A1	0.010	0.100	0.000	0.004
A2	0.150REF.		0.006REF.	
D	0.950	1.050	0.037	0.041
E	0.550	0.650	0.022	0.026
D1	0.500REF.		0.020REF.	
E1	0.450REF.		0.018REF.	
b	0.250	0.350	0.010	0.014
b1	0.100	0.200	0.004	0.008
e	0.635REF.		0.025REF.	
e1	0.300	0.400	0.012	0.016
L	0.200	0.300	0.008	0.012
L1	0.050REF.		0.002REF.	
L2	0.270	0.370	0.011	0.015

WBFBP-03E Suggested Pad Layout



Note:

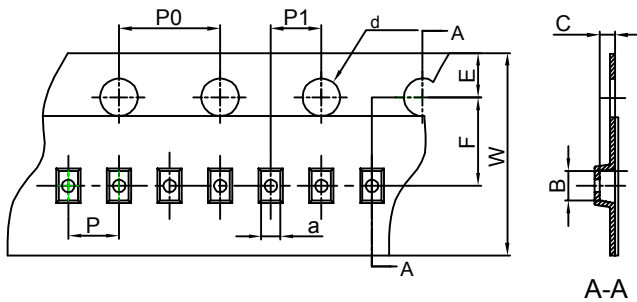
1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.050\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

JSCJ reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

WBFBP-03E(1.0×0.6×0.5) Tape and Reel

WBFBP-03E(1.0×0.6×0.5) Embossed Carrier Tape

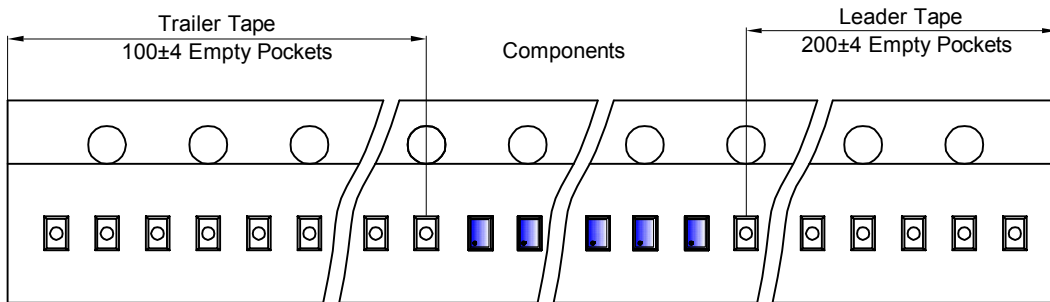


Packaging Description:

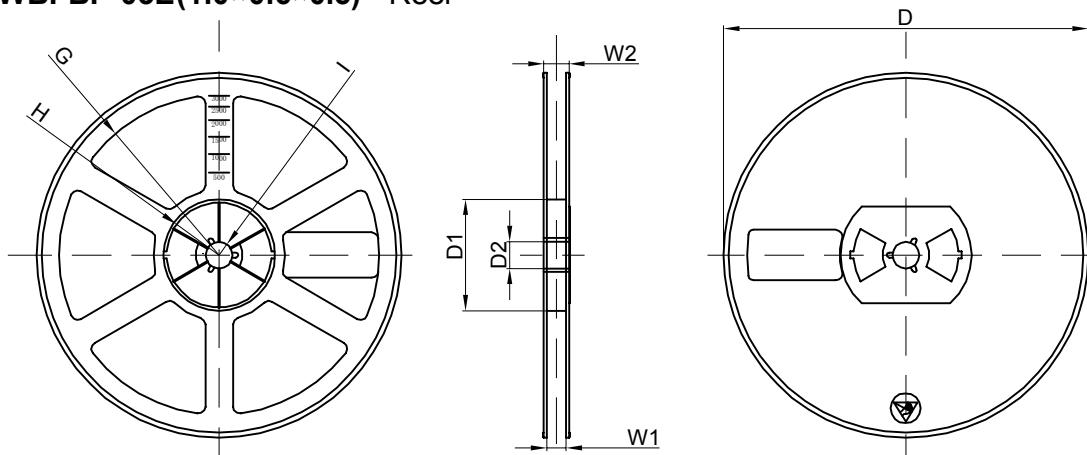
WBFBP-03E(1.0×0.6×0.5) parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 10,000 units per 7" or 17.8cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
WBFBP-03E(1.0×0.6×0.5)	0.66	1.15	0.66	Ø1.50	1.75	3.50	4.00	2.00	2.00	8.00

WBFBP-03E(1.0×0.6×0.5) Tape Leader and Trailer



WBFBP-03E(1.0×0.6×0.5) Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
7"Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
10000 pcs	7 inch	150,000 pcs	203×203×195	600,000 pcs	438×438×220	